

PR/097823 | 2.5D / 3D Assembly Engineer

募集職種

人材紹介会社
ジェイ エイ シー リクルートメント シンガポール

求人ID
1621110

業種
電気・電子・半導体

雇用形態
正社員

勤務地
シンガポール

給与
経験考慮の上、応相談

更新日
2026年11月03日 10:43

応募必要条件

職務経験
6年以上

キャリアレベル
中途経験者レベル

英語レベル
ネイティブレベル

日本語レベル
無し

最終学歴
短大卒： 準学士号

現在のビザ
日本での就労許可は必要ありません

募集要項

2.5D / 3D Assembly EngineerAbout the Role
We are seeking a highly skilled **2.5D / 3D Assembly Engineer** to support the development and implementation of advanced semiconductor packaging and integration technologies. This role will focus on wafer-level packaging, 2.5D/3D assembly processes, package design optimization, reliability engineering, and advanced technology development.

The successful candidate will play a key role in driving innovation, improving assembly methodologies, collaborating with external partners, and developing next-generation packaging solutions for advanced semiconductor applications.

Key Responsibilities

- Lead the development and optimization of advanced semiconductor packaging and assembly technologies, including 2.5D and 3D integration.
- Support package design, assembly process development, and Design for Manufacturing (DFM) and Design for Test (DFT) initiatives.
- Perform thermo-mechanical, electrical, and reliability analysis using simulation and modeling tools.

- Investigate and resolve packaging, assembly, and reliability challenges across various operating environments.
- Collaborate with cross-functional teams, suppliers, and manufacturing partners to drive technology development and process improvements.
- Conduct failure analysis, root-cause investigations, and reliability assessments to improve product performance.
- Support the introduction of new materials, packaging technologies, and assembly methodologies.
- Contribute to technical documentation, design guidelines, and continuous improvement initiatives.

Requirements

- Master's or PhD in Mechanical Engineering, Materials Science, Physics, Semiconductor Packaging, Micro/Nanofabrication, or a related discipline.
- Strong hands-on experience in semiconductor assembly, packaging, or advanced integration technologies.
- Experience with wafer-level packaging, 2.5D/3D packaging, and advanced assembly processes.
- Knowledge of semiconductor package structures, materials, manufacturing processes, and reliability considerations.
- Familiarity with CAD tools and thermo-mechanical simulation methodologies.
- Experience with Finite Element Modeling (FEM) for thermal, mechanical, or electrical analysis.
- Strong understanding of assembly-related failure mechanisms and reliability engineering.
- Excellent analytical, troubleshooting, and engineering problem-solving skills.
- Solid understanding of material properties, physics fundamentals, and package behavior across varying environmental conditions.

Preferred Qualifications

- Experience developing Process Design Kits (PDKs) or packaging design flows.
- Knowledge of Through-Silicon Via (TSV), silicon processing, and thin-film technologies.
- Experience with cryogenic testing or low-temperature electro-mechanical characterization.
- Exposure to high-voltage or power semiconductor packaging qualification.
- Background in process engineering, manufacturing engineering, or advanced packaging development.

Notice: By submitting an application for this position, you acknowledge and consent to the disclosure of your personal information to the Privacy Policy and Terms and Conditions, for the purpose of recruitment and candidate evaluation.

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会社説明